

These assemblies are ESD sensitive, ESD precautions shall be observed. Use of no clean flux is not acceptable. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable. These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

TEXAS INSTRUMENTS
TIDA-01050

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Layer 1 - Top Layer	Copper	1.40mil		
4	Dielectric 1	370HR	5.20mil	4.2	
5	Layer 2 - GND	Copper	1.42mil		
6	Dielectric 2	370HR	43.00mil	4.2	
7	Layer 3 - PWR	Copper	1.42mil		
8	Dielectric 3	370HR	5.20mil	4.2	
9	Layer 4 - Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 20 MIL
 MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
 HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

FR-408 FR-4 High Tg OTHER
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/-
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/-

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES
 PTH COPPER THICKNESS: 20-30 um OTHER

BOARD FINISH:

SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER
 SOLDER RESIST COLOR: GREEN OTHER
 MATTE SEMI-GLOSS

SURFACE FINISH: IMMERSION GOLD (ENIG) ENIG
 1MM. TIN/SILVER OR EQUIV OTHER

ARRAY/PANEL: CUT AND TRIM PER M1 BOARD OUTLINE
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

ANSI IPC-A-600F CLASS -> 1 2 3
 RoHS OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
 PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

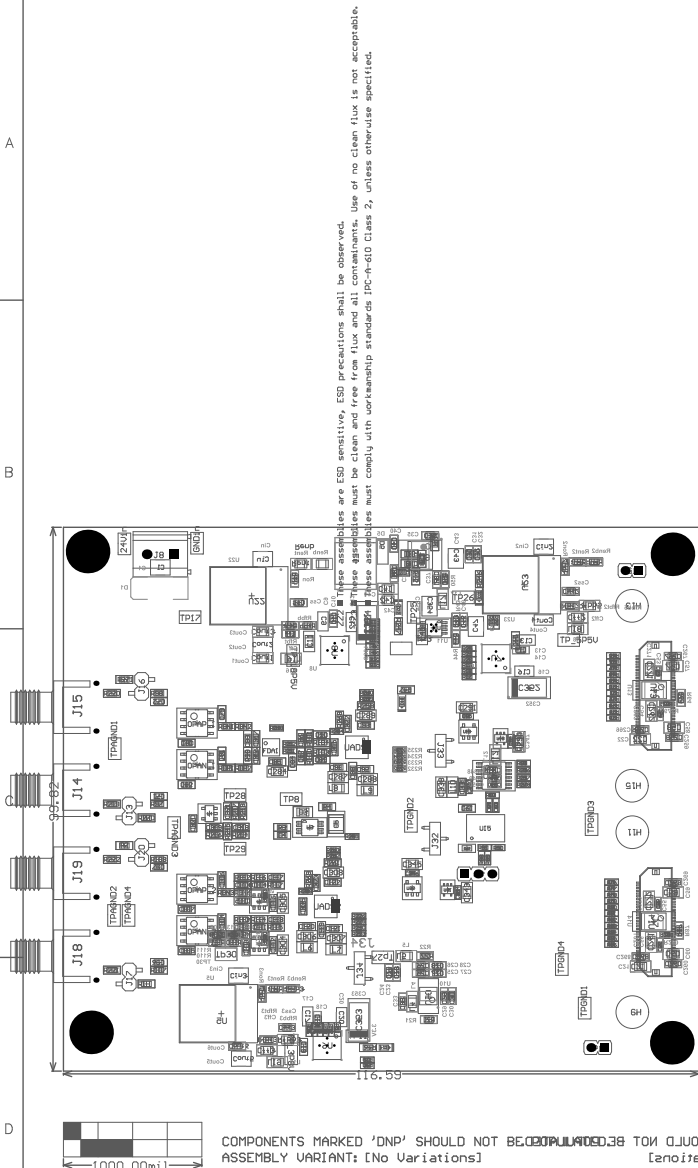


PROJECT TITLE:
OPA625 ADC Driver

DESIGNED FOR:
Public Release

FILE NAME:
OPA625 ADC Driver.PcbDoc

ADDITIONAL COMMENTS:	BOARD #010501050#	DATE: 11/07/2014	DESIGNED BY: TARAS DUDAR	DESIGNED FOR: PUBLIC RELEASE	FILE NAME: OPA625 ADC Driver.PcbDoc
LAYER NAME = TOP LAYER	TID #: 0105010	# DIT	SCALE: 1.00	ALTIM DESIGNER VERSION: 16.1.12.290	
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 OTHER +/- _____
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REFERENCE: AS SHOWN NC_DRILL FILES
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 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR: GREEN OTHER _____
 MATTE SEMI-GLOSS

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPIG
 100% TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER M1 BOARD OUTLINE
 N.C. ROUTE V. SCORE

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 ANSI IPC-A-600F CLASS -> 1 2 3
 RoHS OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
 PCB MUST BEAR THE UL94-V0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

COMPONENTS MARKED 'DNP' SHOULD NOT BE PURCHASED. TO BE PURCHASED, THE PART NUMBER SHOULD BE CHANGED TO THE PART NUMBER IN THE BOM.

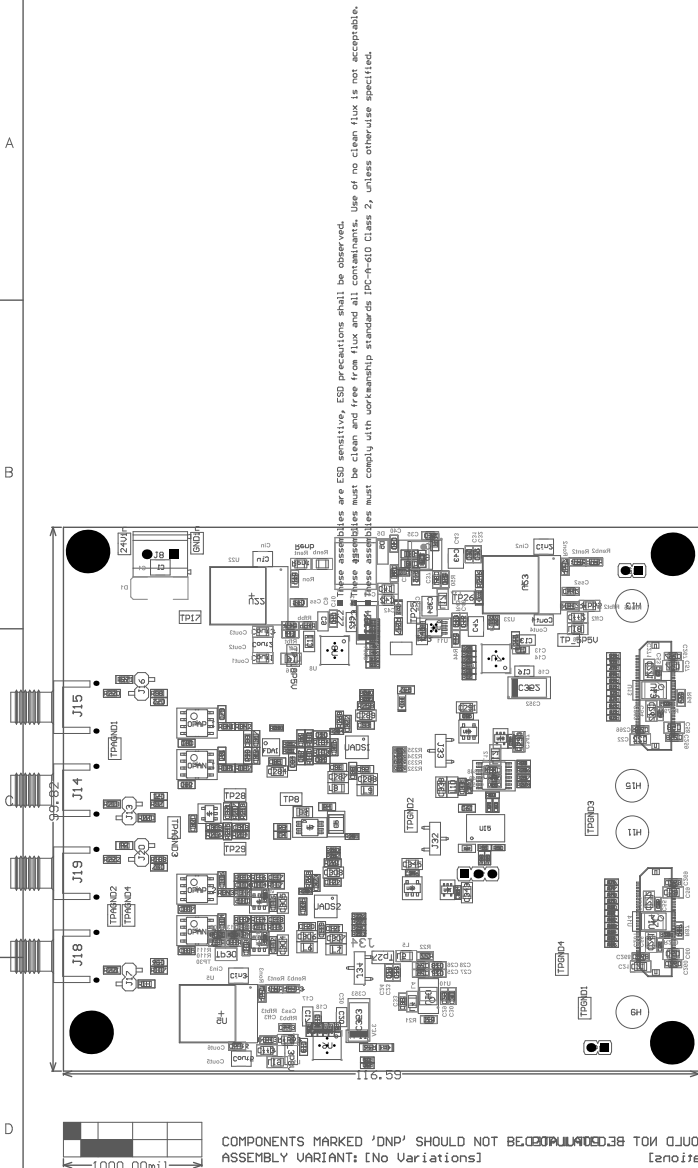
ASSEMBLY VARIANT: [No Variations]

1000.00mil

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PROJECT TITLE: OPA625 ADC Driver
 DESIGNED FOR: Public Release
 FILE NAME: OPA625 ADC Driver.PcbDoc

ENGINEER: Taras Dudar
 SCALE: 1.00
 ALTIUM DESIGNER VERSION: 16.1.12.230



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ARRAY/PANEL:
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 RoHS OTHER PER ORDER

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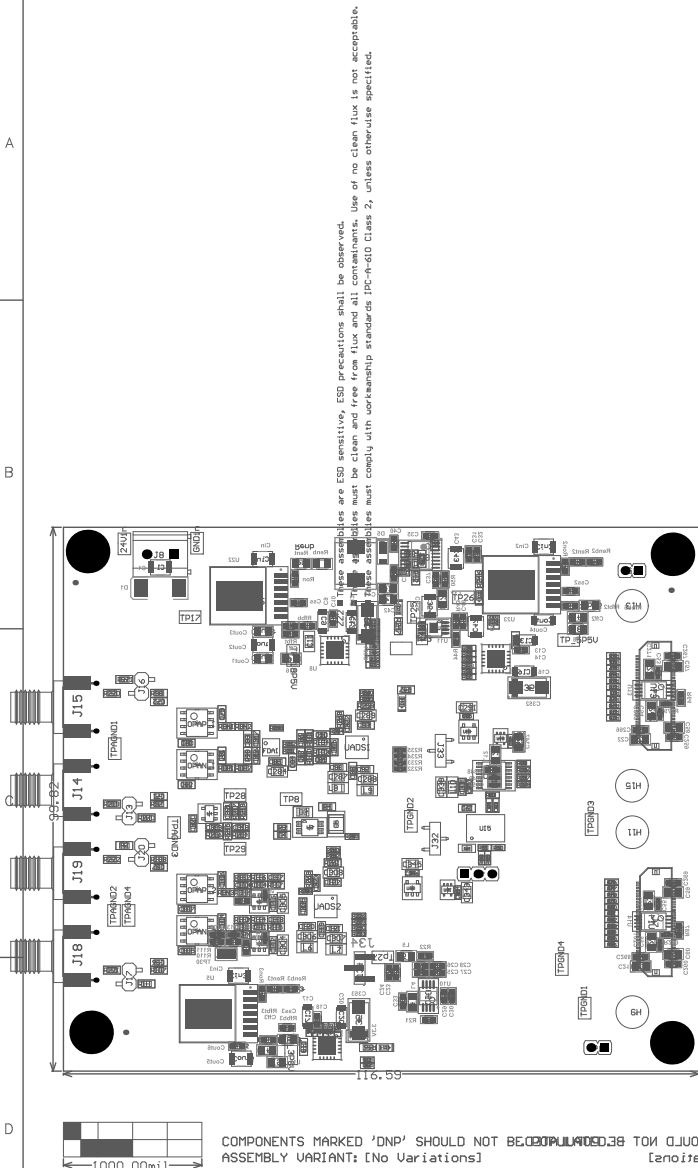
DESIGNED FOR:
Public Release

FILE NAME:
OPA625 ADC Driver.PcbDoc

ADDITIONAL COMMENTS:	DATE:	DESIGNED BY:	DESIGNED FOR:	FILE NAME:	SCALE:	ALTIM DESIGNER VERSION:
ADDITIONAL COMMENTS:	DATE: 11/27/13	DESIGNED BY: TARAS DUDAR	DESIGNED FOR: Public Release	FILE NAME: OPA625 ADC Driver.PcbDoc	SCALE: 1.00	ALTIM DESIGNER VERSION: 16.1.12.230

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1 2 3 4 5 6



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 PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER



PROJECT TITLE:
 OPA625 ADC Driver
 DESIGNED FOR:
 Public Release
 FILE NAME:
 OPA625 ADC Driver.PcbDoc

PCB LAYER NAME = Bottom Layer (Copper) TID #: 0106010 :# D1T
 PLOT NAME = Bottom Layer (Copper) TID #: 0106010 :# D1T

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ENGINEER:
 Taras Dudar
 SCALE: 1.00
 ALTIUM DESIGNER VERSION:
 16.1.12.230

1 2 3 4 5 6

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